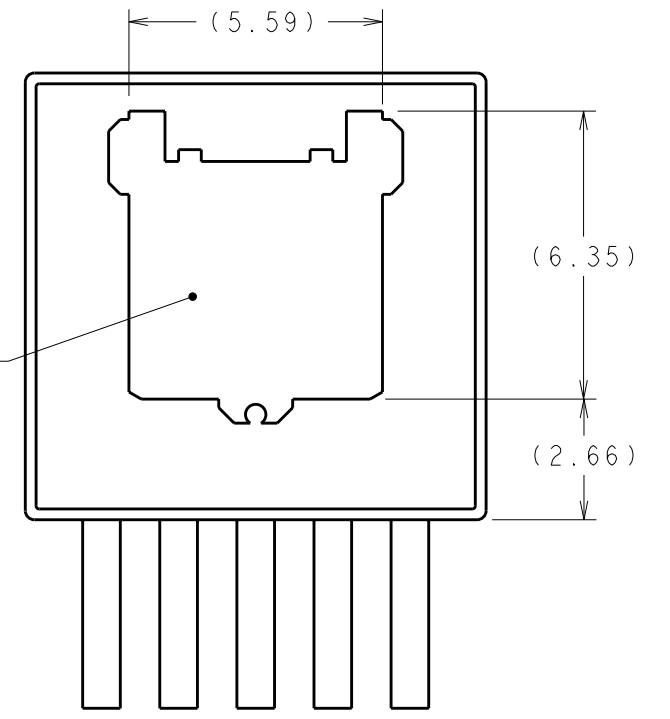
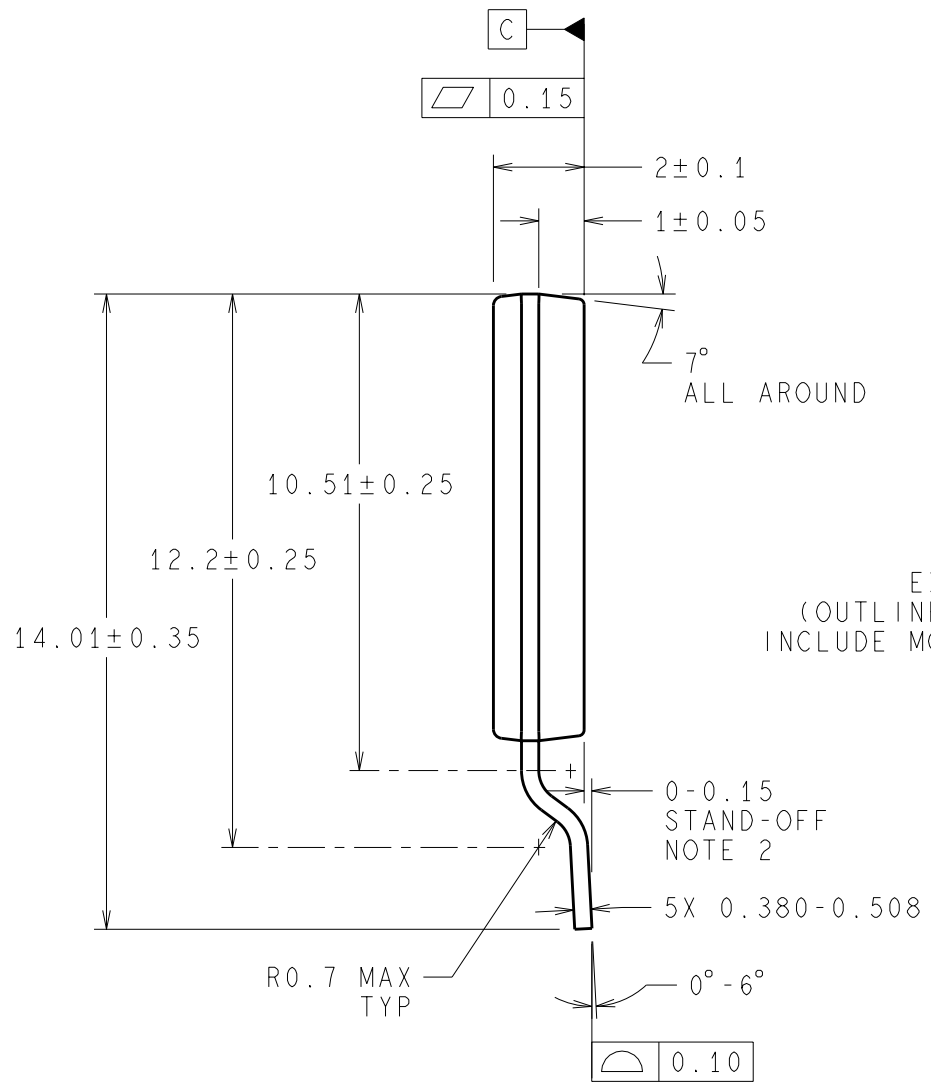
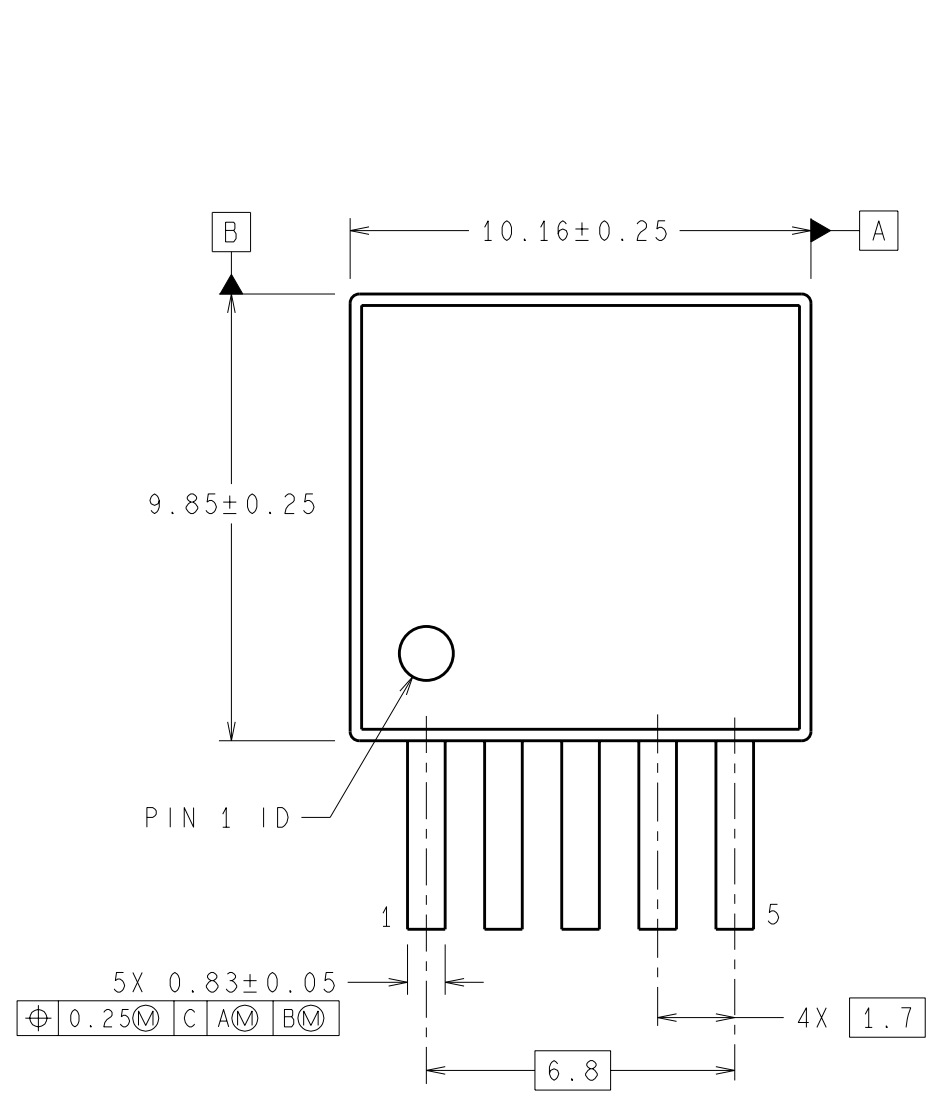
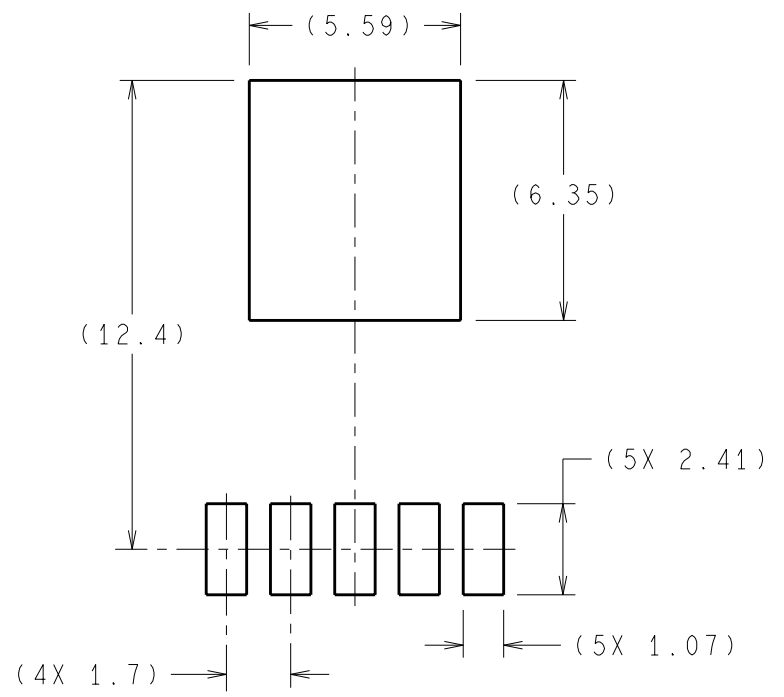


REVISIONS				
REV	DESCRIPTION	E.C.N.	DATE	BY/APP'D
A	RELEASE TO DOCUMENT CONTROL	1805	05/23/2005	AS/TL/AS
B	ADD LEAD COPLANARITY, PKG BOTT FLATNESS, LEAD TIP ANGLE & NEW NOTE 2; CHANGE RECOMMENDED LAND PATTERN DIMENSIONS: 5.59 WAS 7.59, 6.35 WAS 8.35 & 12.4 WAS 13.4	1846	06/14/2005	AS/TL/AS
C	DWG TITLE: CHANGE FROM TO-247 TO THIN TO-263	2024	02/21/2006	AS/MS/AS
D	UPDATE EXPOSED DAP; UPDATE NOTE 3	2393	09/06/2007	AS/TL/EL
E	UPDATE EXPOSED DAP & NOTE 3; ADD OUTLINE DOES NOT INCLUDE MOLD FLASH UNDER EXPOSED DAP	2453	01/02/2008	AS/TL/EL
F	1. UPDATE JEDEC REGISTRATION AT NOTE 3 2. UPDATE OF SOLDER PLATING INFORMATION AT NOTE 1	14447	12/20/2011	FTG//TKY/EL



DIMENSIONS ARE IN MILLIMETERS
DIMENSIONS IN () FOR REFERENCE ONLY



RECOMMENDED LAND PATTERN

NOTES: UNLESS OTHERWISE SPECIFIED

- FOR SOLDER THICKNESS AND COMPOSITION, SEE THE "Lead Finish Composition/Thickness" LINK IN THE PACKAGING SECTION OF THE TEXAS INSTRUMENTS WEB SITE (www.national.com/packaging).
- UNDER ALL CONDITIONS, LEADS MUST NOT BE ABOVE DATUM C.
- REFERENCE JEDEC REGISTRATION AS TO-279, VARIATION BB.

APPROVALS		DATE	TEXAS INSTRUMENTS INC.	
DRAWN	SULAIMAN & LEQUANG	05/23/2005	2900 Semiconductors Operations	
DFTG. CHK.	TK Y.I.I	12/20/2011	THIN TO-263, MOLDED,	
ENGR. CHK.	EUGENE LEE	12/20/2011	9.85x10.16x2mm,	
			5 LD, 1.7mm PITCH, SMT	
PROJECTION	SCALE	SIZE	DRAWING NUMBER	REV
MM	NTS	B	(SC)MKT-TJ5A	F
FORMERLY: N/A			SHEET 1 of 1	